I CLAIM:

1. An improved structure of a hot packing including a plurality of hot packing bag bodies and an electric heating structure, and the contents of the bag bodies being sodium acetate solution and iron plate, characterized in that

the surrounding edges of the hot packing bag bodies are connectedly sealed and a separate lamination layer is formed between a bag body with a second bag body for the mounting of an electric heating plate, a fastening ring for fastening is provided at the wire passage area for the hot packing bag and the electric heating plate so as to completely seal the bag body to avoid leakage and the electric heating plate is provided with a temperature control element, and an external connected temperature regulator and timer so as to effectively control the heat emission of the electric heating plate at a specific temperature so as to avoid excessive temperature to break the bag body.

2. An improved structure of a hot packing as set forth in Claim 1, wherein the electric heating plate is slightly smaller than the hot packing bag and the heat emission object on the electric heating plate is a loop structure such that every corners of the hot packing back can evenly emit heat.

3. An improved structure of a hot packing as set forth in Claim 1, wherein the hot packing bag surface is provided with a plurality of heat melting points such that the top and bottom surface of the hot packing bag are appropriately combined to avoid the contents of the bag body accumulate at a specific area.

4. An improved structure of a hot packing as set forth in Claim 1, wherein the center of the electric heating plate is provided with an appropriate large through hole such that the top and bottom hot packing bag can be combined at the through hole by means of the heat melting points.

5. An improved structure of a hot packing as set forth in Claim 1, wherein the surface of the timer is provided with a rotating button and the surrounding edge of the rotating button is provided with markings.

6. An improved structure of a hot packing as set forth in Claim 1, wherein the hot packing bag contains a non-conductive liquid or solid.

7. An improved structure of a hot packing as set forth in Claim 1, wherein the electric heating plate is a semiconductor cold/hot chip and the top and bottom surface of the cold/hot chip close to the hot packing bag is provided with a heat reduction plate.